

/ Descriptions

TO-220 N MOS N-CHANNEL MOSFET in a TO-220 Plastic Package.

/ Features

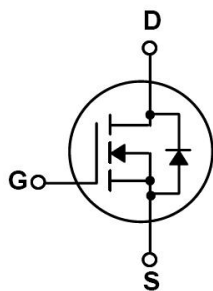
Low gate charge, low crss, fast switching.

/ Applications

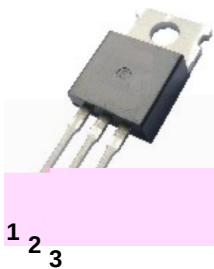
GF2GF

These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

/ Equivalent Circuit



/ Pinning

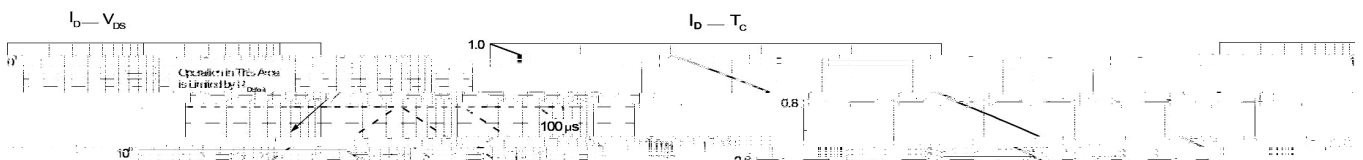
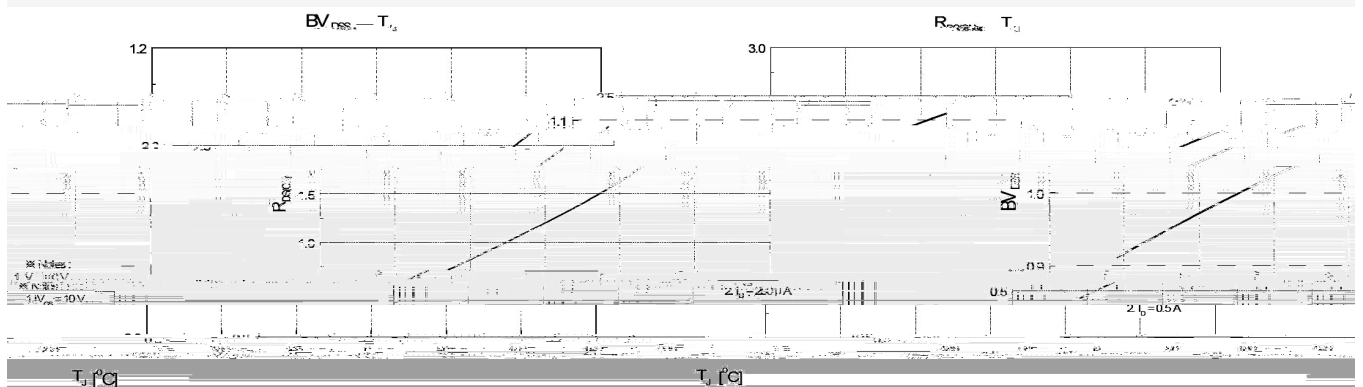
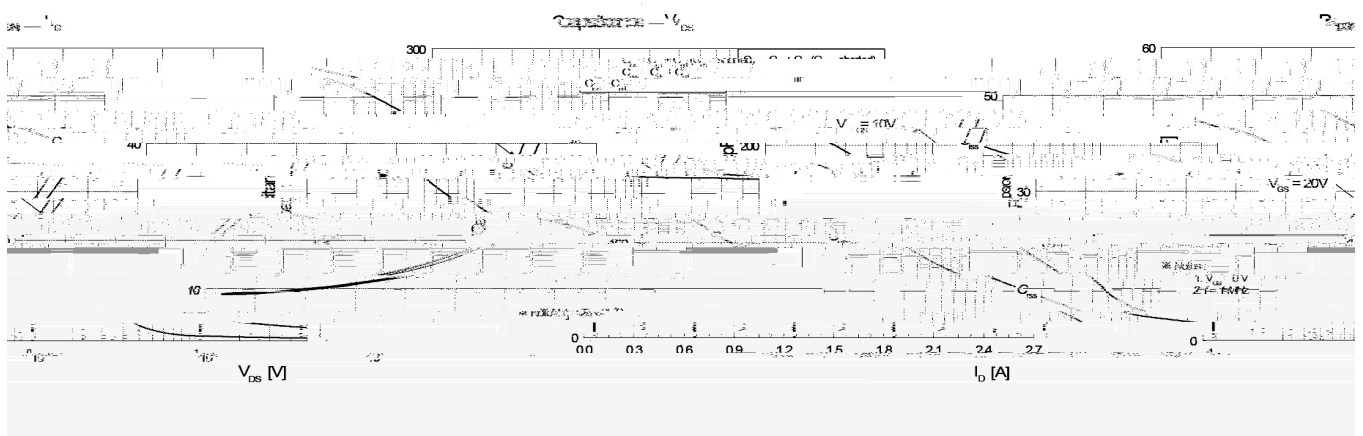
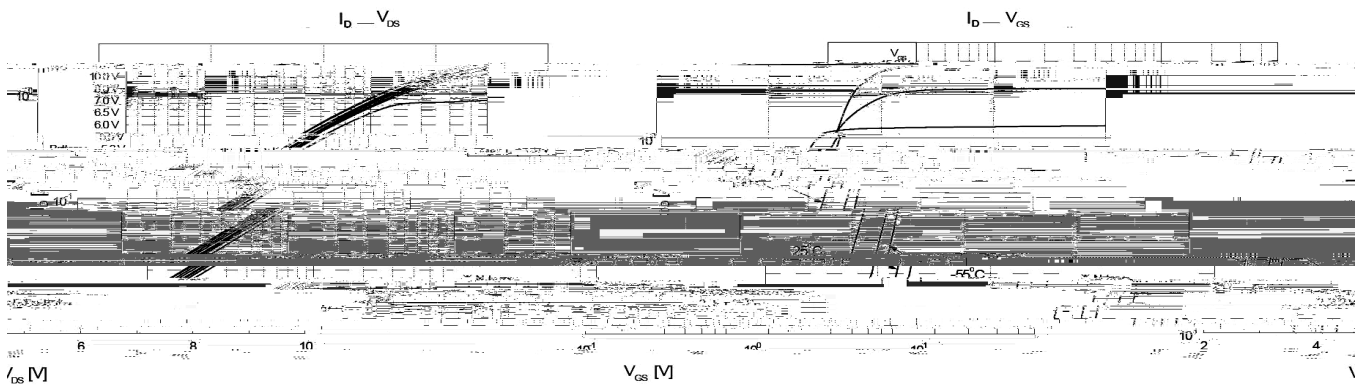


PIN1 G PIN 2 D PIN 3 S

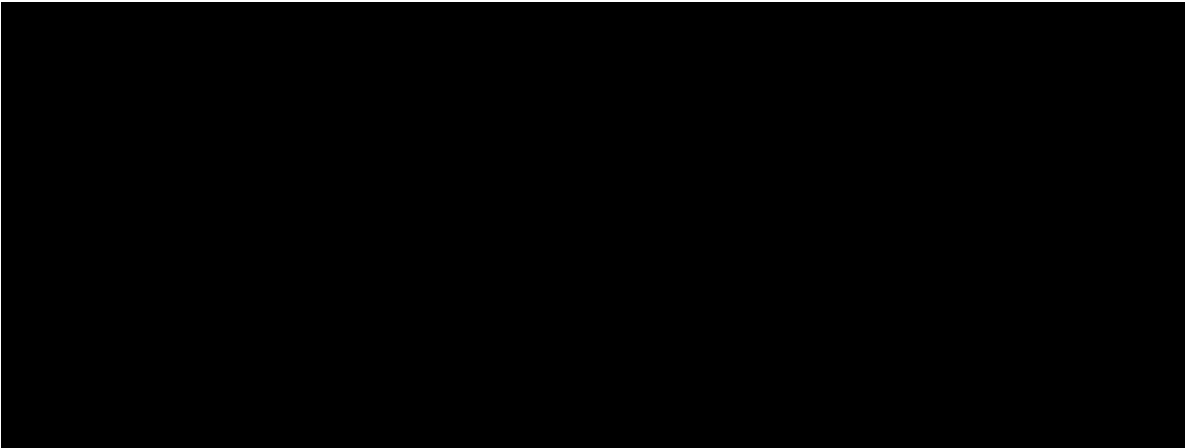
/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Electrical Characteristic Curve

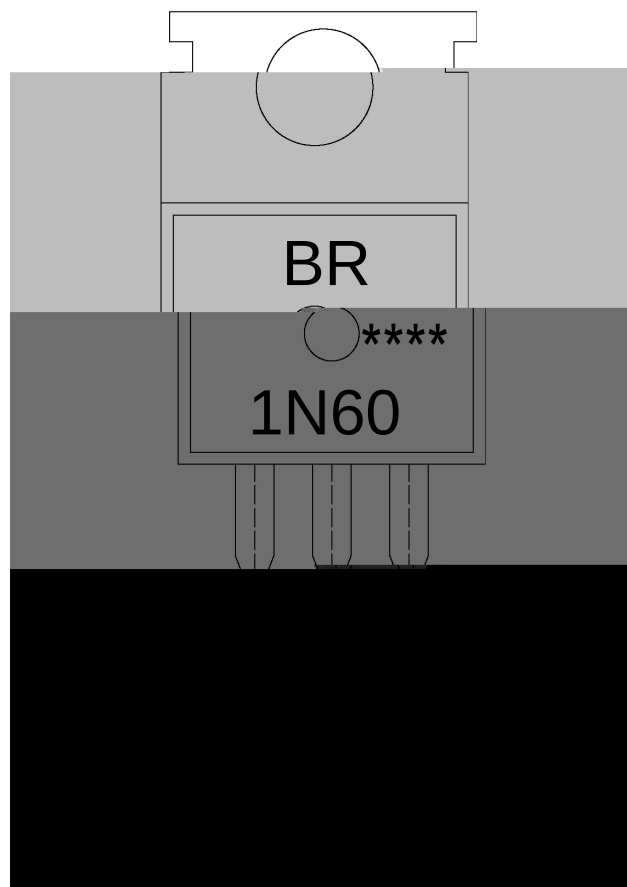


/ Package Dimensions



Dimensions in Millimeters				Dimensions in Millimeters			
Symbol	Max	Symbol	Max	Symbol	Max	Symbol	Max
A	14.7	Δ	9.8	B	10.2	C	12.7
a	6.7	D	3.56	d	0.64	E	16.3
a1	9.4	E	15.7	e	16.1	F	9.0
b	6.4	F	12.2	f	0.61	G	12.0
b1	8.6	G	1.6	g	0.7	H	1.2
c	2.2	H	0.7	h	1.02	I	1.2
c1	1.25	I	1.45	i	0.7	J	1.2

/ Marking Instructions



BR

1N60

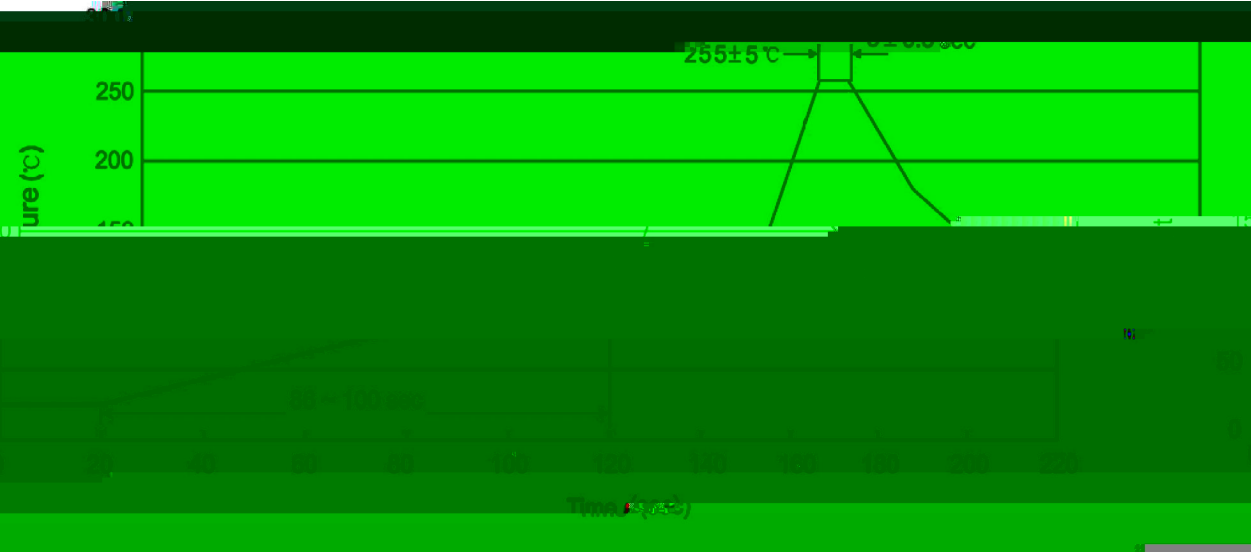
Note:

BR: Company Code

1N60: Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|----|---|----|--------------------------------------|--|
| 1 | 25 | 150 ³ / ₈ | 60 | 90sec; | 1.Preheating:25~150 ³ / ₈ , Time:60~90sec. |
| 2 | | 255 ² / ₅ ³ / ₈ | | 5 ² / _{0.5} sec; | 2.Peak Temp.:255 ² / ₅ ³ / ₈ , Duration:5 ² / _{0.5} sec. |
| 3 | | | 2 | 10 ³ / ₈ /sec. | 3. Cooling Speed: 2~10 ³ / ₈ /sec. |

/ Resistance to Soldering Heat Test Conditions

270²/₅³/₈ 10²/₁ sec. Temp.:270±5